TE0820 - HD Banks

Title: TE0820 - HD Banks

Copyright: Trenz Electronic GmbH / TT

Date: 2018-03-29

File: B_HD.SchDoc
```plaintext
Title: TE0820 - B65
Number: TE0820
03EG-1EB
Date: 2018-03-28
Copyright: Trenz Electronic GmbH / TT
Page: 6

Title: TE0820 - B65
Number: TE0820
03EG-1EB
Date: 2018-03-28
Copyright: Trenz Electronic GmbH / TT
Page: 6
```
CHANGES REV01 to REV02

1) Added MAC EEPROM (slave address)
2) LIB components update
3) Fixed SD Card connection
4) Fixed sense connection from DCDC
5) Made correct power connection for VCU (removed DCDC, added capacitors as Xilinx recommended)
6) Added resistors for variants (ZU+ with/without VCU)
7) Added termination resistors (240R) to VRP pins for all HP-banks

CHANGES REV02 to REV03

1) Fixed VCU connection: add additional DCDC (0.9V)
2) LIB components update
3) Change package 1K resistors (0402 -> 0201)
4) Added LEDs (1x user LED, 1x LED for ERR STATUS, 1xLED for ERR_OUT)
5) Change obsolete 2xSPI Flash (256MBit) -> 2xSPI Flash (512MBit)
6) Added additional DCDCs (PL_VCCINT_IO, PS_FP0V85)
7) Changed DCDC (U5) 6A (optional 4A)